

## PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Cheng-Liang Cheng</td><td>05/04/2007</td></tr><tr><td>Kuo-Ching Cheng</td><td>05/09/2007</td></tr><tr><td>Yi-Hsiu Pan</td><td>05/04/2007</td></tr><tr><td>Bang-Hao Wu</td><td>05/04/2007</td></tr><tr><td>Li-Duan Tsai</td><td>05/04/2007</td></tr></tbody></table>	Name	Execution Date	Cheng-Liang Cheng	05/04/2007	Kuo-Ching Cheng	05/09/2007	Yi-Hsiu Pan	05/04/2007	Bang-Hao Wu	05/04/2007	Li-Duan Tsai	05/04/2007	
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RECEIVING PARTY DATA													
<table border="1"><tr><td>Name:</td><td>Industrial Technology Research Institute</td></tr><tr><td>Street Address:</td><td>No. 195, Section 4, Chung Hsing Road, Chutung,</td></tr><tr><td>City:</td><td>Hsinchu</td></tr><tr><td>State/Country:</td><td>TAIWAN</td></tr></table>	Name:	Industrial Technology Research Institute	Street Address:	No. 195, Section 4, Chung Hsing Road, Chutung,	City:	Hsinchu	State/Country:	TAIWAN					
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PROPERTY NUMBERS Total: 1													
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11766802</td></tr></tbody></table>	Property Type	Number	Application Number:	11766802									
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CORRESPONDENCE DATA													
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NAME OF SUBMITTER:	Belinda Lee												
Total Attachments: 2 source=22546assignment#page1.tif													

CH 11766802 \$40.00

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PATENT  
REEL: 019515 FRAME: 0743



## ASSIGNMENT

WHEREAS,

- |                      |                    |
|----------------------|--------------------|
| 1. Cheng-Liang Cheng | 2. Kuo-Ching Cheng |
| 3. Yi-Hsiu Pan       | 4. Bang-Hao Wu     |
| 5. Tsai, Li-Duan     |                    |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **SOLID ELECTROLYTIC CAPACITOR AND LEAD FRAME THEREOF**

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute  
of No. 195, Section 4, Chung Hsing Road, Chutung, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

P54950113US  
22546-US-PA

## ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Cheng-Liang Cheng  
Sole or First Joint Inventor: Cheng-Liang Cheng

Date: 5-4-2007

Signature: Kuo-Ching Cheng  
Second Joint Inventor (if any): Kuo-Ching Cheng

Date: 7-MAY-2007

Signature: Yi-Hsiu Pan  
Third Joint Inventor (if any): Yi-Hsiu Pan

Date: 5-4-2007

Signature: Bang-Hao Wu  
Fourth Joint Inventor (if any): Bang-Hao Wu

Date: 5-4-2007

Signature: Li-Duan Tsai  
Fifth Joint Inventor (if any): Li-Duan Tsai

Date: 5-4-2007